

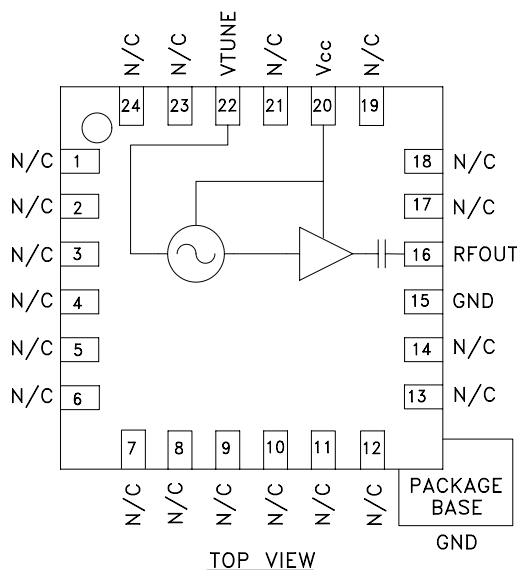
## MMIC VCO w/ BUFFER AMPLIFIER, 2.05 - 2.25 GHz

### Typical Applications

Low noise MMIC VCO w/Buffer Amplifier for:

- Wireless Infrastructure
- Industrial Controls
- Test Equipment
- Military

### Functional Diagram



### Features

Pout: +3.5 dBm

Phase Noise: -112 dBc/Hz @100 KHz

No External Resonator Needed

Single Supply: 3V @ 35 mA

QFN Leadless SMT Package, 16 mm<sup>2</sup>

### General Description

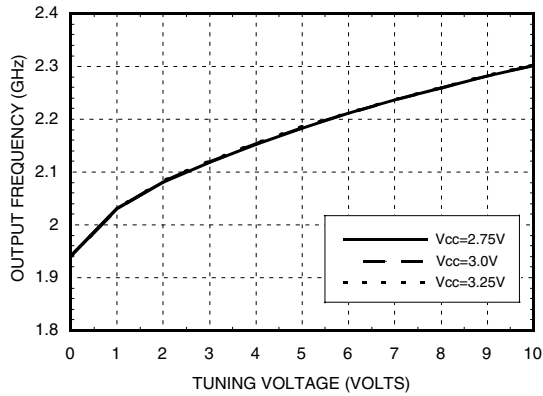
The HMC384LP4 is a GaAs InGaP Heterojunction Bipolar Transistor (HBT) MMIC VCO with integrated resonator, negative resistance device, varactor diode, and buffer amplifier. The VCO's phase noise performance is excellent over temperature, shock, vibration and process due to the oscillator's monolithic structure. Power output is 3.5 dBm typical from a 3.0V supply voltage. The voltage controlled oscillator is packaged in a low cost leadless QFN 4 x 4 mm surface mount package.

### Electrical Specifications, $T_A = +25^\circ\text{C}$ , $V_{CC} = +3\text{V}$

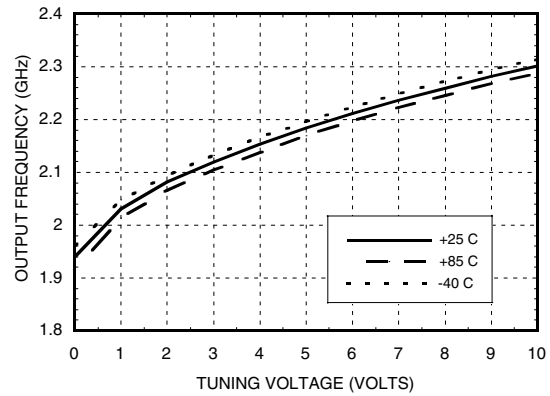
| Parameter                                                             | Min.        | Typ.      | Max. | Units                 |
|-----------------------------------------------------------------------|-------------|-----------|------|-----------------------|
| Frequency Range                                                       | 2.05 - 2.25 |           |      | GHz                   |
| Power Output                                                          | 0.5         | 3.5       |      | dBm                   |
| SSB Phase Noise @ 100 kHz Offset, $V_{tune} = +5\text{V}$ @ RF Output |             | -112      |      | dBc/Hz                |
| Tune Voltage ( $V_{tune}$ )                                           | 0           |           | 10   | V                     |
| Supply Current ( $I_{CC}$ ) ( $V_{CC} = +3.0\text{V}$ )               |             | 35        |      | mA                    |
| Tune Port Leakage Current                                             |             |           | 10   | $\mu\text{A}$         |
| Output Return Loss                                                    |             | 6         |      | dB                    |
| Harmonics<br>2nd<br>3rd                                               |             | -7<br>-23 |      | dBc<br>dBc            |
| Pulling (into a 2.0:1 VSWR)                                           |             | 2.5       |      | MHz pp                |
| Pushing @ $V_{tune} = +5\text{V}$                                     |             | 5         |      | MHz/V                 |
| Frequency Drift Rate                                                  |             | 0.25      |      | MHz/ $^\circ\text{C}$ |

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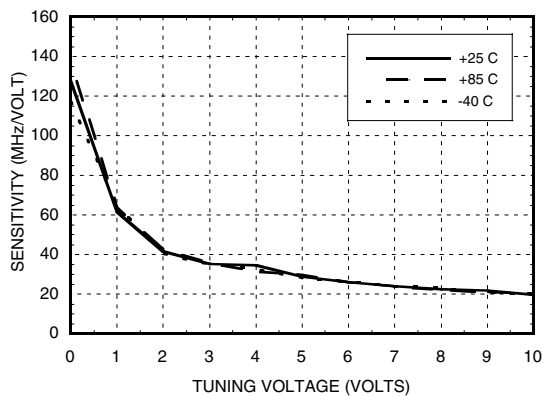
**Frequency vs. Tuning Voltage,  $T = 25^\circ\text{C}$**



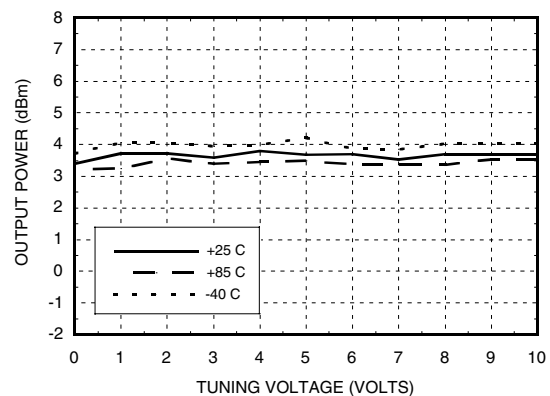
**Frequency vs. Tuning Voltage,  $V_{cc} = +3V$**



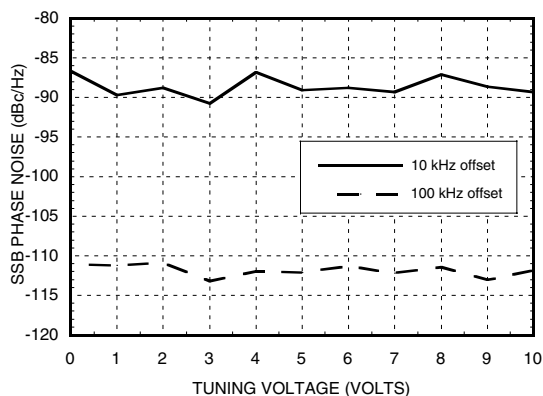
**Sensitivity vs. Tuning Voltage,  $V_{cc} = +3V$**



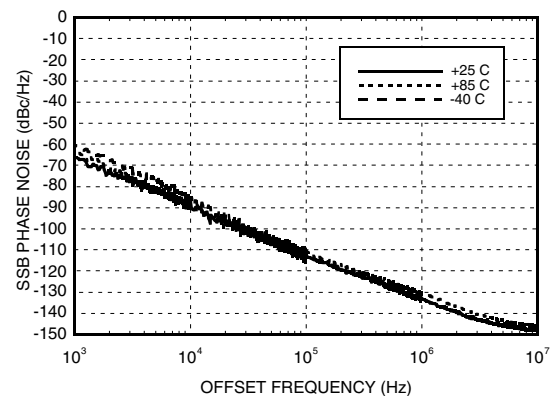
**Output Power vs.  
Tuning Voltage,  $V_{cc} = +3V$**



**Phase Noise vs. Tuning Voltage**



**Typical SSB Phase Noise @  $V_{tune} = +5V$**



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### Absolute Maximum Ratings

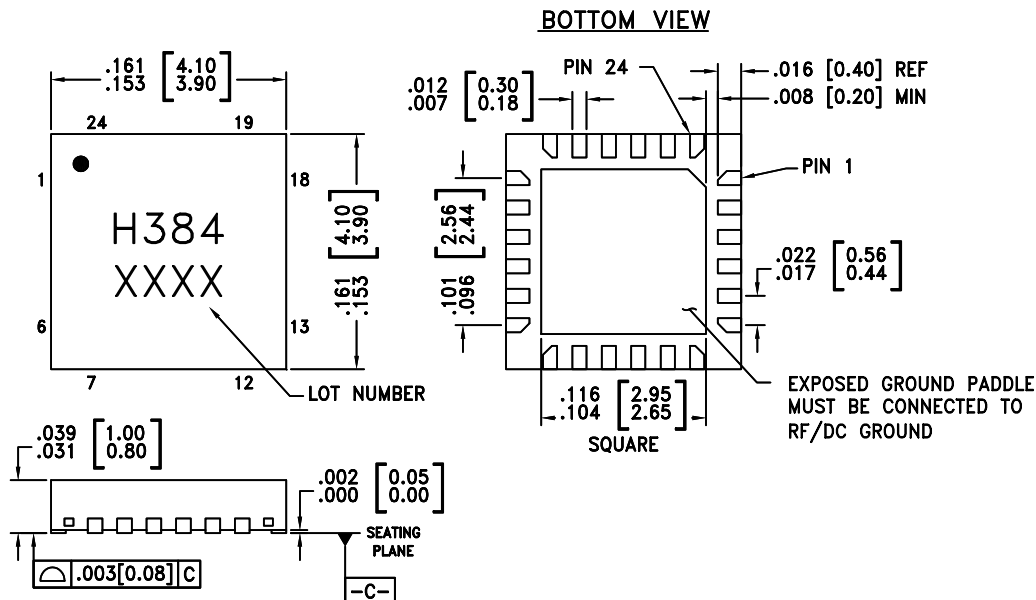
|                                                               |                |
|---------------------------------------------------------------|----------------|
| Vcc                                                           | +3.5 Vdc       |
| Vtune                                                         | 0 to +11V      |
| Channel Temperature                                           | 135 °C         |
| Continuous Pdiss (T = 85°C)<br>(derate 6.28 mW/°C above 85°C) | 565 W          |
| Storage Temperature                                           | -65 to +150 °C |
| Operating Temperature                                         | -40 to +85 °C  |

### Typical Supply Current vs. Vcc

| Vcc (V) | Icc (mA) |
|---------|----------|
| 2.75    | 28       |
| 3.0     | 35       |
| 3.25    | 41       |

Note: VCO will operate over full voltage range shown above.

### Outline Drawing

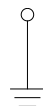
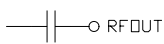
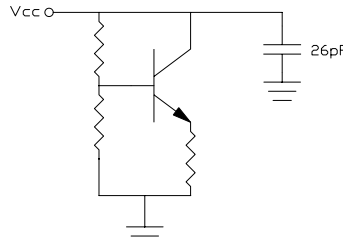
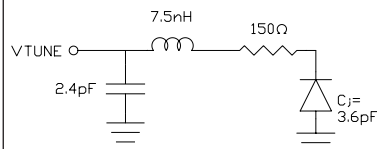


#### NOTES:

1. MATERIAL PACKAGE BODY: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY
3. LEAD AND GROUND PADDLE PLATING: Sn/Pb SOLDER
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
6. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.  
PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
7. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
9. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

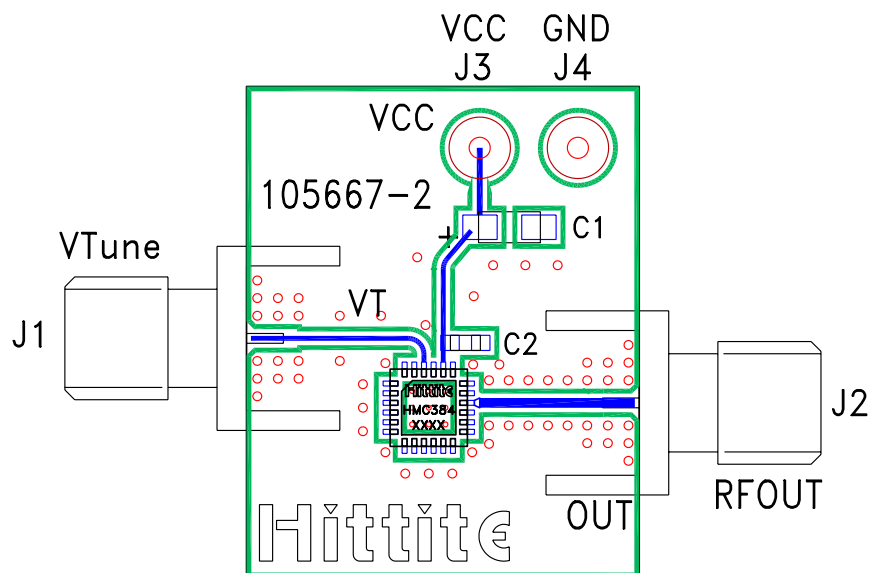
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### Pin Descriptions

| Pin Number                    | Function | Description                                                                           | Interface Schematic                                                                   |
|-------------------------------|----------|---------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------|
| 1- 14, 17 - 19,<br>21, 23, 24 | N/C      | No Connection                                                                         |                                                                                       |
| 15                            | GND      | This pin must be connected to RF & DC ground.                                         |    |
| 16                            | RFOUT    | RF output (AC coupled)                                                                |    |
| 20                            | Vcc      | Supply Voltage Vcc= 3V                                                                |   |
| 22                            | VTUNE    | Control Voltage Input. Modulation port bandwidth dependent on drive source impedance. |  |
|                               | GND      | Package bottom has an exposed metal paddle that must be RF & DC grounded.             |  |

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### Evaluation PCB



### List of Materials

| Item                                  | Description                    |
|---------------------------------------|--------------------------------|
| J1 - J2                               | PC Mount SMA RF Connector      |
| J3 - J4                               | DC Pin                         |
| C1                                    | 4.7 µF Tantalum Capacitor      |
| C2                                    | 10,000 pF Capacitor, 0603 Pkg. |
| U1                                    | HMC384LP4 VCO                  |
| PCB*                                  | 105667 Eval Board              |
| * Circuit Board Material: Rogers 4350 |                                |

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

## ***MMIC VCO w/ BUFFER AMPLIFIER, 2.05 - 2.25 GHz***

### ***Notes:***